

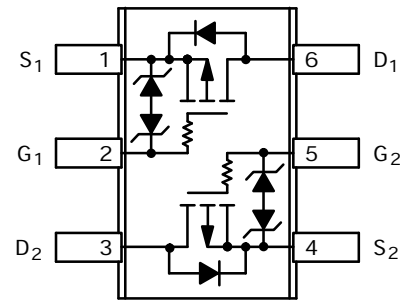
P-Channel Enhancement Mode Power MOSFET

Description

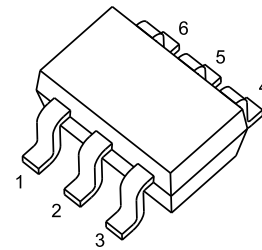
The RMD0A8P20ES9 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

- $V_{DS} = -20V, I_D = -0.8A$
 $R_{DS(ON)} < 800 \text{ m}\Omega @ V_{GS} = -4.5V$
 $R_{DS(ON)} < 1200m\Omega @ V_{GS} = -2.5V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package
- Halogen-free
- P/N suffix V means AEC-Q101 qualified, e.g:RMD0A8P20ES9V



Top View



SOT-363

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
0A8P20	RMD0A8P20ES9	SOT-363-6L	Ø180mm	8mm	3000units

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	P-Channel	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	-0.8	A
Pulsed Drain Current ^(Note 1)	I_{DM}	-4	A
Maximum Power Dissipation	P_D	0.8	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	156	$^\circ\text{C/W}$
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Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

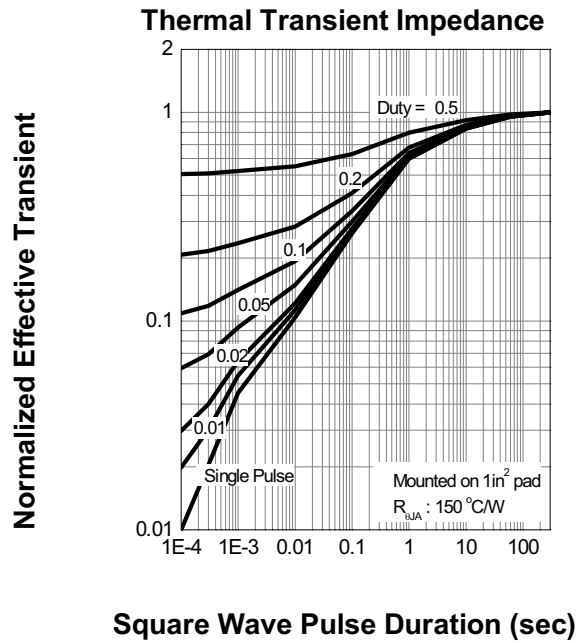
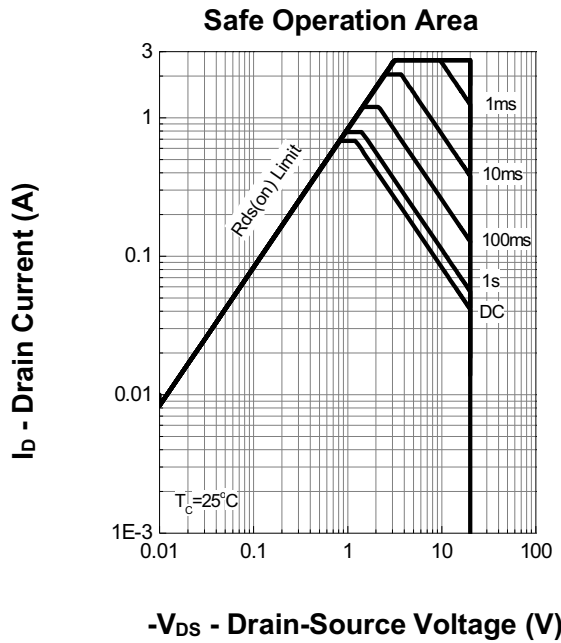
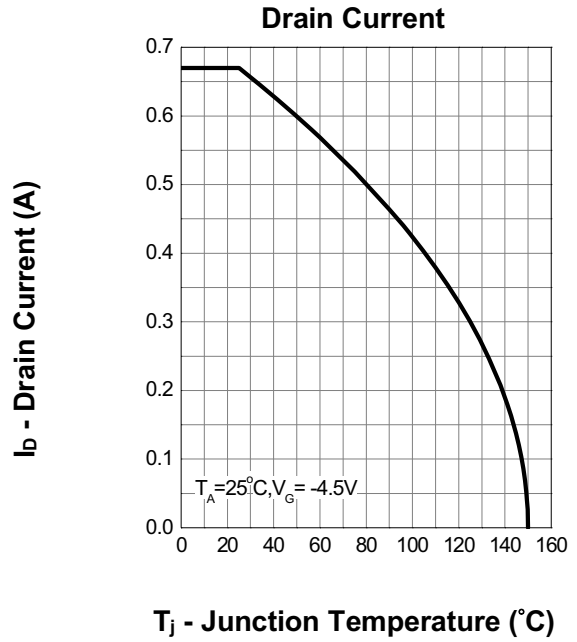
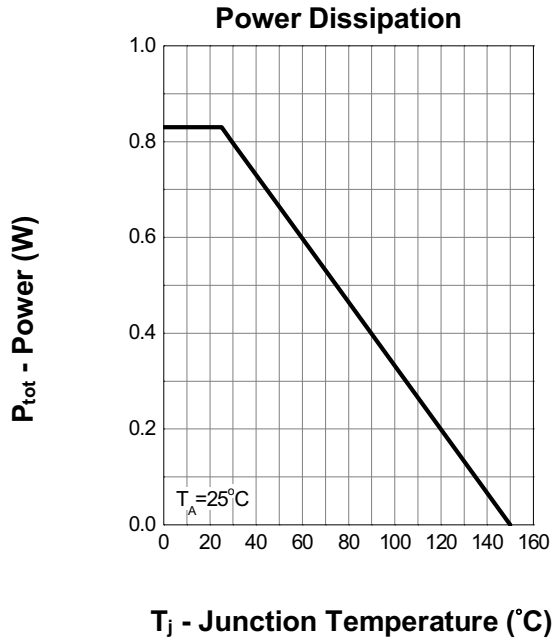
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_{DS} = -250\text{ }\mu\text{A}$	-20	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = -250\text{ }\mu\text{A}$	-0.3	-0.65	-1.0	V
I_{DSS}	Drain Leakage Current	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$	-	-	-1	μA
		$T_J = 85\text{ }^\circ\text{C}$	-	-	-30	μA
I_{GSS}	Gate Leakage Current	$V_{GS} = \pm 8\text{ V}, V_{DS} = 0\text{ V}$	-	-	± 10	μA
$R_{DS(ON)}^a$	On-State Resistance	$V_{GS} = -4.5\text{ V}, I_{DS} = -0.5\text{ A}$	-	0.85	1.2	Ω
		$V_{GS} = -2.5\text{ V}, I_{DS} = -0.2\text{ A}$	-	1.05	1.5	
		$V_{GS} = -1.5\text{ V}, I_{DS} = -0.04\text{ A}$	-	1.5	-	
		$V_{GS} = -1.2\text{ V}, I_{DS} = -0.01\text{ A}$	-	2	-	
Diode Characteristics						
V_{SD}^a	Diode Forward Voltage	$I_{SD} = -0.5\text{ A}, V_{GS} = 0\text{ V}$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$I_{SD} = -0.5\text{ A}, dI_{SD}/dt = 100\text{ A}/\mu\text{s}$	-	70	-	ns
Q_{rr}	Reverse Recovery Charge		-	68	-	nC
Dynamic Characteristics^b						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = -10\text{ V}$ Frequency = 1 MHz	-	87	-	pF
C_{oss}	Output Capacitance		-	15	-	
C_{rss}	Reverse Transfer Capacitance		-	8.2	-	
$t_d(on)$	Turn-on Delay Time	$V_{DS} = -30\text{ V}, V_{GEN} = -10\text{ V},$ $R_G = 25\text{ }\Omega, R_L = 60\text{ }\Omega,$ $I_{DS} = -0.67\text{ A}$	-	5.6	-	ns
t_r	Turn-on Rise Time		-	5.3	-	
$t_d(off)$	Turn-off Delay Time		-	30	-	
t_f	Turn-off Fall Time		-	21	-	
Q_g	Total Gate Charge	$V_{GS} = -4.5\text{ V}, V_{DS} = -10\text{ V},$ $I_{DS} = -0.67\text{ A}$	-	1.8	-	pC
Q_{gs}	Gate-Source Charge		-	0.82	-	
Q_{gd}	Gate-Drain Charge		-	0.59	-	

Notes :

a : Pulse test ; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

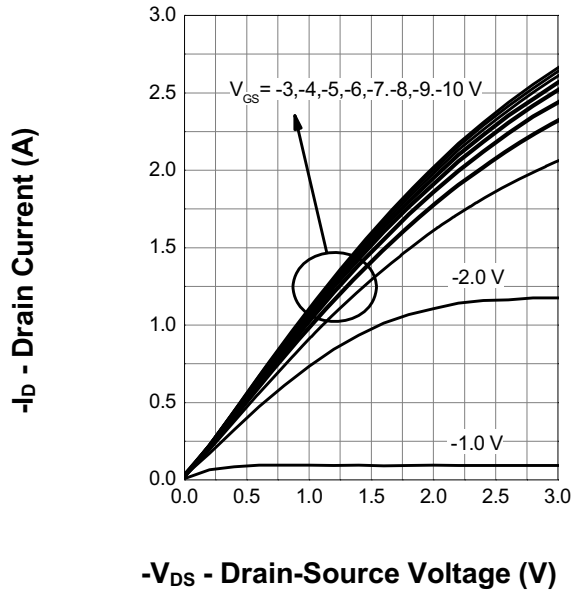
b : Guaranteed by design, not subject to production testing

RATING AND CHARACTERISTICS CURVES (RMP0A8P20ES9)

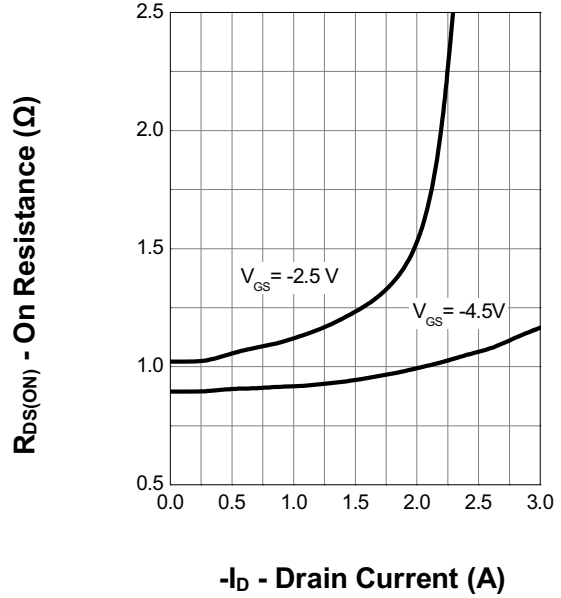


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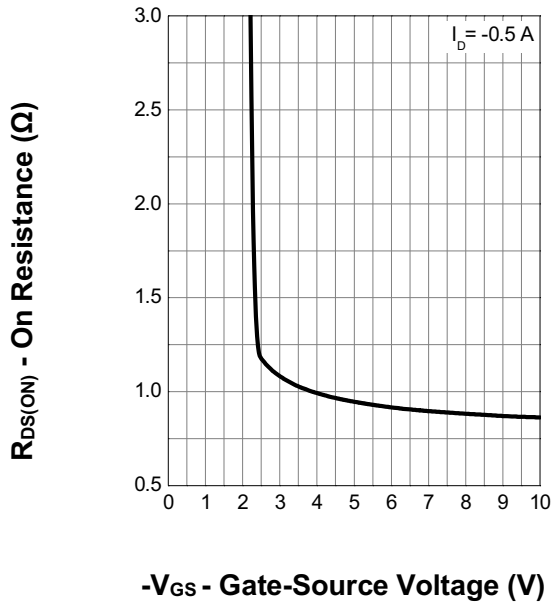
Output Characteristics



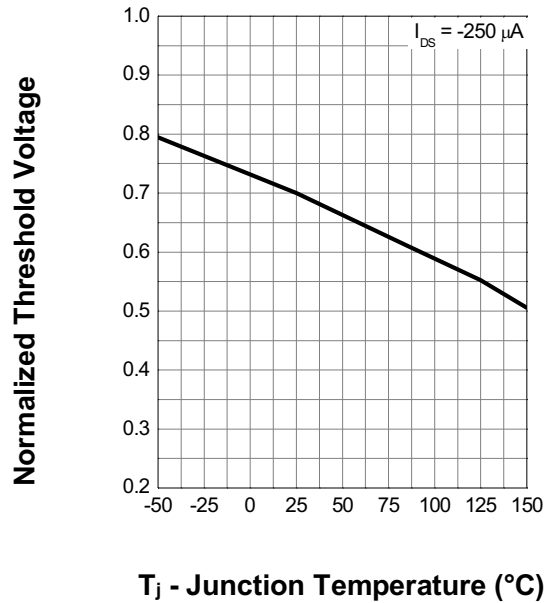
Drain-Source On Resistance



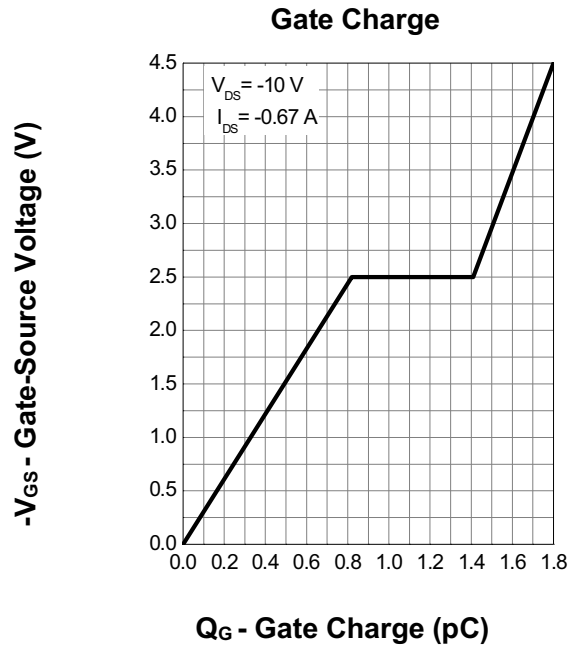
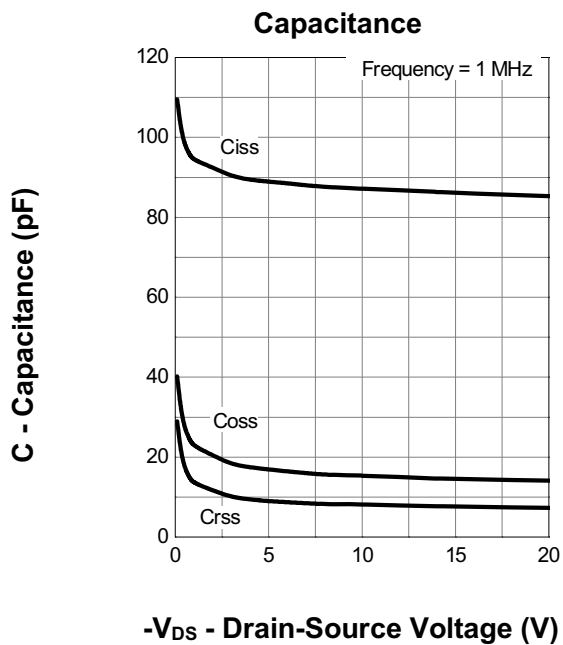
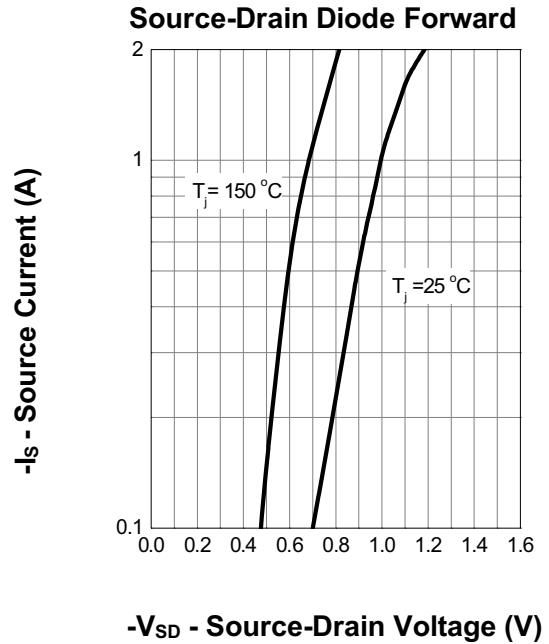
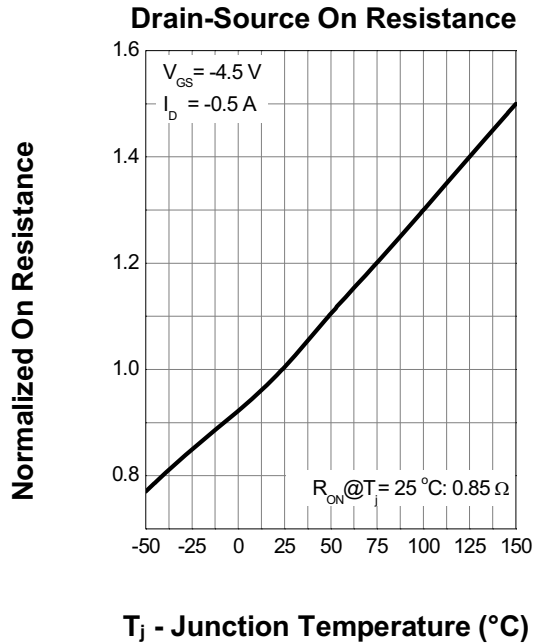
Transfer Characteristics



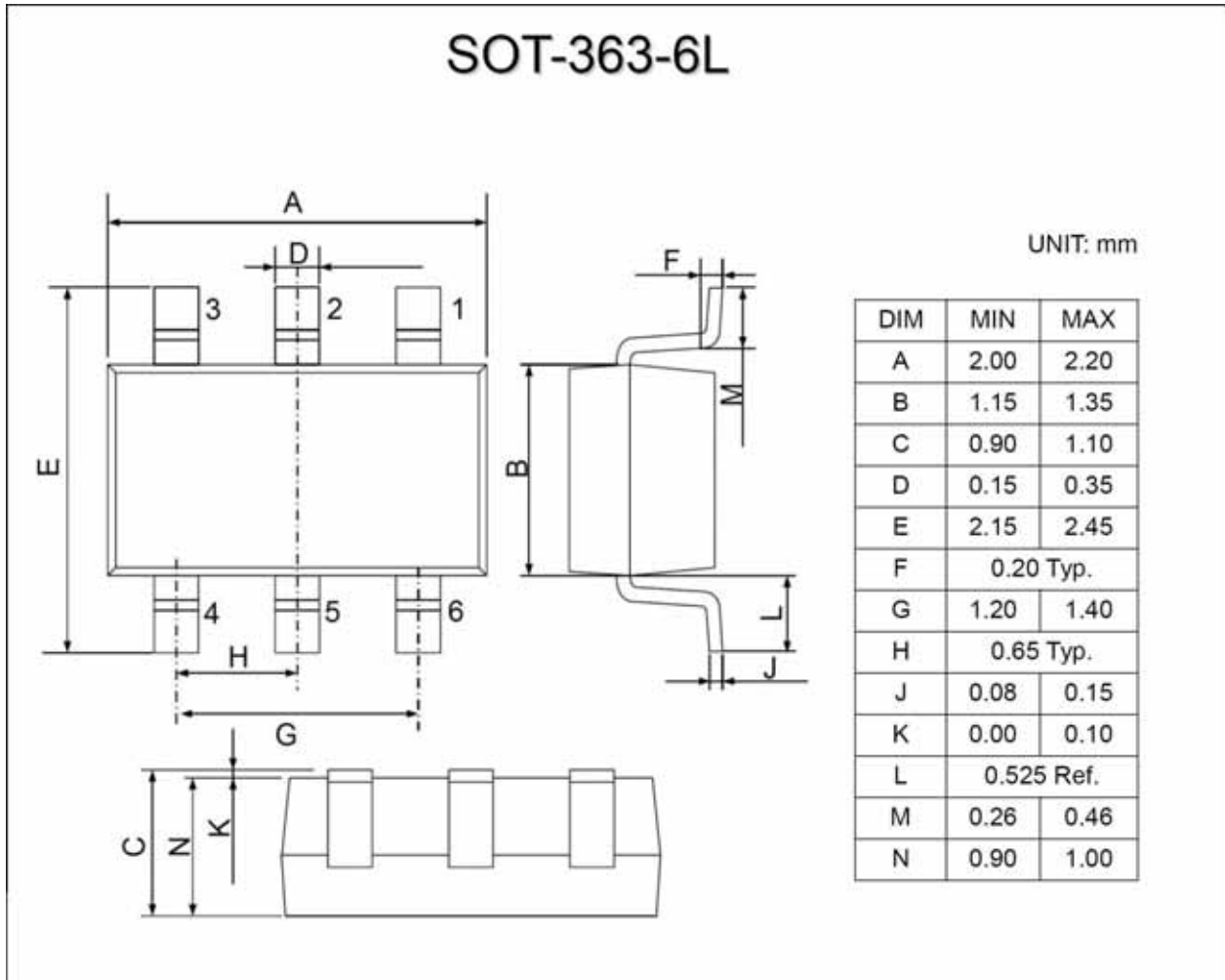
Gate Threshold Voltage



RATING AND CHARACTERISTICS CURVES (RMP0A8P20ES9)



Package Dimensions



PKG	Reel	Box	pcs/reel	reel/box	pcs/box	box/carton	pcs/carton
SOT363	7"		3000	10	30000	4	120000